

ABSTRACT OF THE DISCLOSURE

A socket for a microelectronic component is provided. The socket has a base with metal power and ground layers, and further includes a plurality of electrically conductive socket members, some of which are connected in parallel to the metal power layer, others being connected in parallel to the metal ground layer, while others are insulated from both the metal power and ground layers for purposes of providing signals. Each electrically conductive socket member has a protrusion that breaks through an inner insulating layer that defines an opening into which the electrically conductive socket member is inserted. The protrusions are at different heights, so that some of the protrusions make contact with the metal power layer, while others are connected to the metal ground layer or to a dielectric core layer.